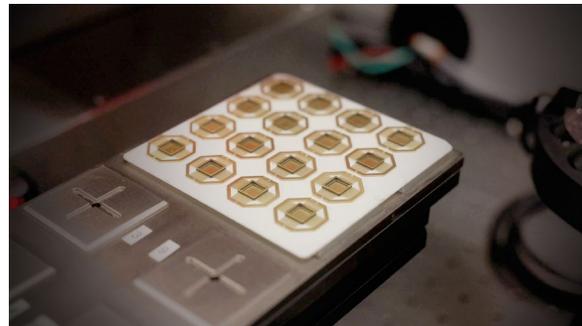


FOR IMMEDIATE RELEASE

## StratEdge Packaging and Assembly Services Expands for High-Frequency and High-Power Devices

*Technical experts available at BCICTS 2022 and IMAPS 2022  
to discuss packaging applications*

Santee, Calif. – September 28, 2022 – [StratEdge Corporation](#), leader in the design, production, and assembly of high-frequency and high-power semiconductor packages for microwave, announces that StratEdge technical experts will be available to discuss the best types of packaging and assembly services for devices from DC to 63+ GHz at the International Symposium for Microelectronics (IMAPS) 2022 and BCICTS. StratEdge will be exhibiting in booth 317 at **IMAPS**, being held in Boston, Massachusetts on Oct. 4-5, and in booth 5 at **BCICTS**, being held in Phoenix, Arizona from Oct. 17-18.



StratEdge designs, manufactures, and provides [assembly services for RF and microwave packages](#) with applications in the telecom, VSAT, broadband wireless, satellite, military, test and measurement, automotive, clean energy, and down-hole markets. The packages have ultra-low losses over wide frequencies. Their high-reliability designs have high thermal conductivity and 50 ohm impedance transition designs.

StratEdge not only makes the packages but provides complete assembly and lidding services for them. Assembly is done in StratEdge's ISO 9001:2015 facility that contains a Class 1000 cleanroom and Class 100 work areas with workstations for performing sensitive operations. Assembly services cover manual to fully automatic wire and die bonding, using wire or ribbon wedge bonding and a proprietary [eutectic die attach technology](#). StratEdge has expertise in assembling microwave and RF devices in California since 1999.

"Working with compound semiconductors, such as gallium nitride, requires a package that can best dissipate the heat from the device while ensuring that the device is performing at its optimum potential," said **Casey Krawiec, VP global sales for StratEdge**. "Although the package plays the most critical part, the way the chip is packaged can also make a significant difference in the device's performance. Please stop by our booth at IMAPS or BCICTS to discuss your application."

For more information, contact StratEdge at [info@stratedge.com](mailto:info@stratedge.com), visit our website at [www.stratedge.com](http://www.stratedge.com), or take a Virtual Tour of StratEdge's newly expanded production facilities at <https://youtu.be/ewJuORN5vyQ>.

Photo available at: [www.stratedge.com/packaging-assembly-services.png](http://www.stratedge.com/packaging-assembly-services.png)

## About StratEdge

[StratEdge Corporation](#), founded in 1992, designs, manufactures and provides assembly services for a complete line of high-frequency and high-power semiconductor packages operating from DC to 63+ GHz. StratEdge offers post-fired ceramic, low-cost molded ceramic, and ceramic QFN packages, and specializes in packages for extremely demanding gallium arsenide (GaAs) and gallium nitride (GaN) devices. Markets served include telecom for 5G, VSAT, broadband wireless, satellite, military, test and measurement, automotive, clean energy, and down-hole. All packages are lead-free and most meet RoHS and WEEE standards. StratEdge is ITAR registered and an ISO 9001:2015 certified facility located in Santee, California, near San Diego.

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